L Number	Hits	Search Text	DB	Time stamp
21	35	"257698"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:24
22	1784	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:25
23	2462	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:25
24	2274	438/637	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:26
25	314	438/667	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:26
26	300	438/668	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:28
27	6240	257/698 257/774 438/637 438/667 438/668	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:28
28	995	(257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
29	955	((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:29
30	656	(((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:44
31	189	((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:32
32	18	(((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 14:39
33	8	5767580.URPN.	USPAT	2002/12/27 14:35
34	24	("3339274" | "3461357" | "3811186" | "4151543" | "4545610" | "4664309" | "4700276" | "4717066" | "4801992" | "4825284" | "4857482" | "4912545" | "4926241" | "5006673" | "5014111" | "5077633" | "5108950" | "5111279" | "5196726" | "5311402" | "5404047" | "5468999" | "5477086" | "5525838").PN.	USPAT	2002/12/27 14:36
35	21	5477086.URPN.	USPAT	2002/12/27 14:36
36	7	("3339274" | "3461357" | "4151543" | "4857482" | "5014111" | "5196726" | "5311402").PN.	USPAT	2002/12/27 14:38

41	171	(((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
42	2	6187652.URPN.	USPAT	2002/12/27 14:46
43	0	6486409.URPN.	USPAT	2002/12/27 14:47
44	6	("5210940" | "6013876" | "6080936" | "6187652" | "6198634" | "6252176").PN.	USPAT	2002/12/27 14:47
45	1	6198634.URPN.	USPAT	2002/12/27 14:48
46	23	("4814855" | "5121299" | "5191174" | "5239448" | "5306546" | "5316788" | "5373627" | "5468681" | "5477082" | "5479703" | "5504035" | "5583321" | "5591941" | "5633533" | "5637832" | "5675889" | "5715144" | "5764485" | "5773884" | "5784262" | "5796589" | "5812378" | "5999415").PN.	USPAT	2002/12/27 14:48
47	2	6013876.URPN.	USPAT	2002/12/27 14:57
48	9	5210940.URPN.	USPAT	2002/12/27 15:00
49	9	("3742597" | "4487659" | "4512829" | "4528259" | "4529477" | "4720324" | "4861640" | "4996391" | "5129142").PN.	USPAT	2002/12/27 15:02
50	11	5900674.URPN.	USPAT	2002/12/27 15:14
51	7	("4641222" | "4835704" | "4894115" | "5161093" | "5449427" | "5454904" | "5527741").PN.	USPAT	2002/12/27 15:15
52	4	5783866.URPN.	USPAT	2002/12/27 15:16
53	3	("4082394" | "4322778" | "5569960").PN.	USPAT	2002/12/27 15:17
54	2	"5962922"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
55	4	"5923535"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
56	24	"5097318"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
57	31	"5404044"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
58	9	"5796163"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:20
59	5	"6187652"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:21
60	4	"6114769"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:21

62	76	("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769") not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:22
63	22	(("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769") not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ((ring brace) with (cutoff gap)))) not "5097318" not "5404044"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:22
64	2	6114769.URPN.	USPAT	2002/12/27 15:23
65	13	("5468999" | "5551627" | "5691041" | "5796590" | "5838069" | "5844316" | "5859474" | "5861678" | "5869904" | "5883438" | "5892288" | "5921462" | "5930889").PN.	USPAT	2002/12/27 15:24
66	8	5936848.URPN.	USPAT	2002/12/27 15:25
67	5	("5241133" | "5450290" | "5512786" | "5640047" | "5689091").PN.	USPAT	2002/12/27 15:27
61	78	"5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:29
68	7	("4664962" | "5315072" | "5404044" | "5406034" | "5541368" | "5689091" | "5783865").PN.	USPAT	2002/12/27 15:30
69	8	4664962.URPN.	USPAT	2002/12/27 15:31
70	5	("3384957" | "4045863" | "4366229" | "4436583" | "4512829").PN.	USPAT	2002/12/27 15:31
72	2747	257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:42
73	4597	257/774 257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
74	722	(257/774 257/773) and (solder adj (ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:43
75	709	((257/774 257/773) and (solder adj (ball bump))) and (substrate carrier ((circuit wiring) adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:46
76	336	((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:47
77	325	(((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/27 15:48

| 78 | 246 | (((((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/27 15:48 |
| 79 | 235 | (((((257/774 257/773) and (solder adj (ball bump))) and ((substrate carrier ((circuit wiring) adj board)) near3 (vias (through adj hole)))) and (chip die ic)) not (((((257/698 257/774 438/637 438/667 438/668) and (solder adj (ball bump))) and· (chip die)) and ((substrate carrier tape board film) near4 (hole vias))) and ring)) not ("5962922" "5923535" "5097318" "5404044" "5796163" "6187652" "6114769") | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/27 15:49 |